

MJD2955 (PNP), MJD3055 (NPN)

Complementary Power Transistors

DPAK for Surface Mount Applications

Designed for general purpose amplifier and low speed switching applications.

Features

- Lead Formed for Surface Mount Applications in Plastic Sleeves (No Suffix)
- Straight Lead Version in Plastic Sleeves (“-1” Suffix)
- Electrically Similar to MJE2955 and MJE3055
- High Current Gain-Bandwidth Product
- Epoxy Meets UL 94 V-0 @ 0.125 in
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS

| Rating | Symbol | Max | Unit |
|---|----------------|---------------|--------------------------|
| Collector-Emitter Voltage | V_{CEO} | 60 | Vdc |
| Collector-Base Voltage | V_{CB} | 70 | Vdc |
| Emitter-Base Voltage | V_{EB} | 5 | Vdc |
| Collector Current | I_C | 10 | Adc |
| Base Current | I_B | 6 | Adc |
| Total Power Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C | P_D^\dagger | 20 0.16 | W W/ $^\circ\text{C}$ |
| Total Power Dissipation (Note 1) @ $T_A = 25^\circ\text{C}$ Derate above 25°C | P_D | 1.75 0.014 | W W/ $^\circ\text{C}$ |
| Operating and Storage Junction Temperature Range | T_J, T_{stg} | -55 to +150 | $^\circ\text{C}$ |
| ESD - Human Body Model | HBM | 3B | V |
| ESD - Machine Model | MM | C | V |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

†Safe Area Curves are indicated by Figure 1. Both limits are applicable and must be observed.

1. These ratings are applicable when surface mounted on the minimum pad sizes recommended.

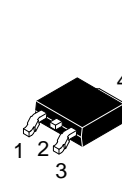
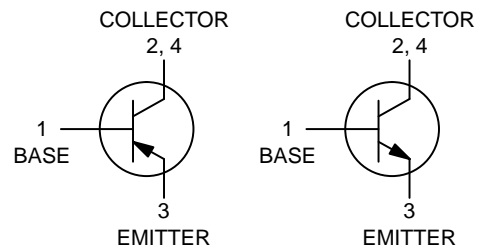


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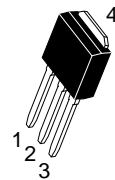
<http://onsemi.com>

SILICON POWER TRANSISTORS 10 AMPERES 60 VOLTS, 20 WATTS

COMPLEMENTARY

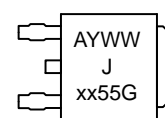


**DPAK
CASE 369C
STYLE 1**

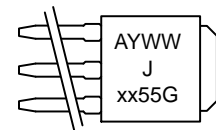


**IPAK
CASE 369D
STYLE 1**

MARKING DIAGRAMS



DPAK



IPAK

- A = Assembly Location
- Y = Year
- WW = Work Week
- Jxx55 = Device Code
x = 29 or 30
- G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

MJD2955 (PNP), MJD3055 (NPN)

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Max | Unit |
|--|-----------------|------|---------------|
| Thermal Resistance, Junction-to-Case | $R_{\theta JC}$ | 6.25 | $^{\circ}C/W$ |
| Thermal Resistance, Junction-to-Ambient (Note 2) | $R_{\theta JA}$ | 71.4 | $^{\circ}C/W$ |

2. These ratings are applicable when surface mounted on the minimum pad sizes recommended.

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted)

| Characteristic | Symbol | Min | Max | Unit |
|----------------|--------|-----|-----|------|
|----------------|--------|-----|-----|------|

OFF CHARACTERISTICS

| | | | | |
|---|---------------|----|------------------|-----------------|
| Collector-Emitter Sustaining Voltage (Note 3) ($I_C = 30 \text{ mAdc}$, $I_B = 0$) | $V_{CE(sus)}$ | 60 | – | Vdc |
| Collector Cutoff Current ($V_{CE} = 30 \text{ Vdc}$, $I_B = 0$) | I_{CEO} | – | 50 | μAdc |
| Collector Cutoff Current ($V_{CE} = 70 \text{ Vdc}$, $V_{EB(off)} = 1.5 \text{ Vdc}$) ($V_{CE} = 70 \text{ Vdc}$, $V_{EB(off)} = 1.5 \text{ Vdc}$, $T_C = 150^{\circ}C$) | I_{CEX} | – | $\frac{0.02}{2}$ | mAdc |
| Collector Cutoff Current ($V_{CB} = 70 \text{ Vdc}$, $I_E = 0$) ($V_{CB} = 70 \text{ Vdc}$, $I_E = 0$, $T_C = 150^{\circ}C$) | I_{CBO} | – | $\frac{0.02}{2}$ | mAdc |
| Emitter Cutoff Current ($V_{BE} = 5 \text{ Vdc}$, $I_C = 0$) | I_{EBO} | – | 0.5 | mAdc |

ON CHARACTERISTICS

| | | | | |
|--|---------------|----------------|-----------------|-----|
| DC Current Gain (Note 3) ($I_C = 4 \text{ Adc}$, $V_{CE} = 4 \text{ Vdc}$) ($I_C = 10 \text{ Adc}$, $V_{CE} = 4 \text{ Vdc}$) | h_{FE} | $\frac{20}{5}$ | $\frac{100}{-}$ | – |
| Collector-Emitter Saturation Voltage (Note 3) ($I_C = 4 \text{ Adc}$, $I_B = 0.4 \text{ Adc}$) ($I_C = 10 \text{ Adc}$, $I_B = 3.3 \text{ Adc}$) | $V_{CE(sat)}$ | – | $\frac{1.1}{8}$ | Vdc |
| Base-Emitter On Voltage (Note 3) ($I_C = 4 \text{ Adc}$, $V_{CE} = 4 \text{ Vdc}$) | $V_{BE(on)}$ | – | 1.8 | Vdc |

DYNAMIC CHARACTERISTICS

| | | | | |
|--|-------|---|---|-----|
| Current-Gain – Bandwidth Product ($I_C = 500 \text{ mAdc}$, $V_{CE} = 10 \text{ Vdc}$, $f = 500 \text{ kHz}$) | f_T | 2 | – | MHz |
|--|-------|---|---|-----|

3. Pulse Test: Pulse Width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 2\%$.

MJD2955 (PNP), MJD3055 (NPN)

TYPICAL CHARACTERISTICS

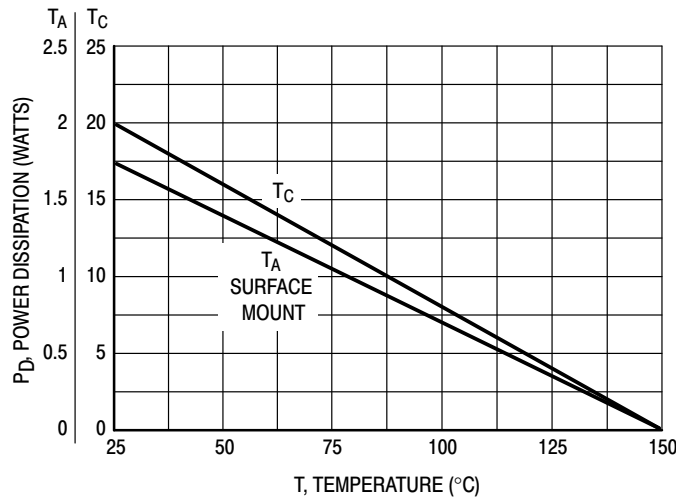


Figure 1. Power Derating

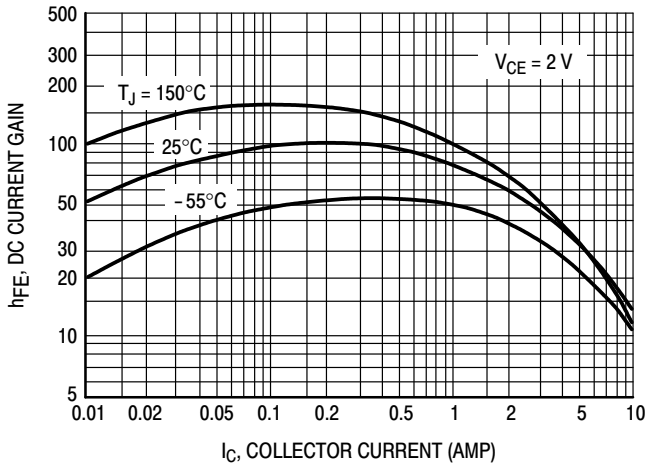


Figure 2. DC Current Gain

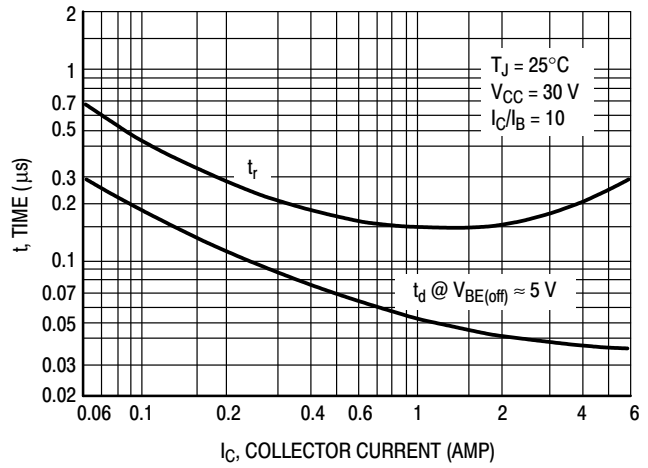


Figure 3. Turn-On Time

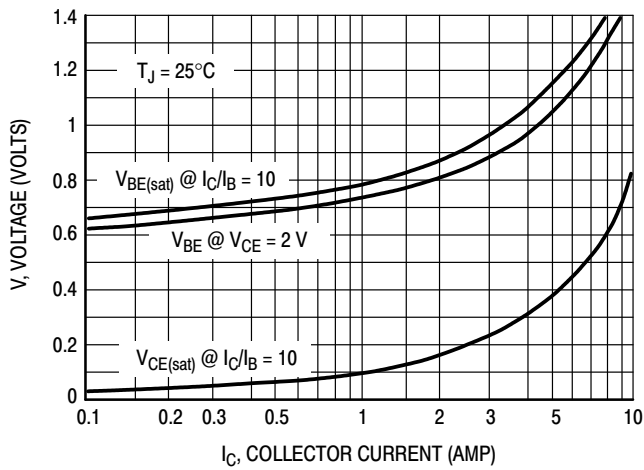


Figure 4. "On" Voltages, MJD3055

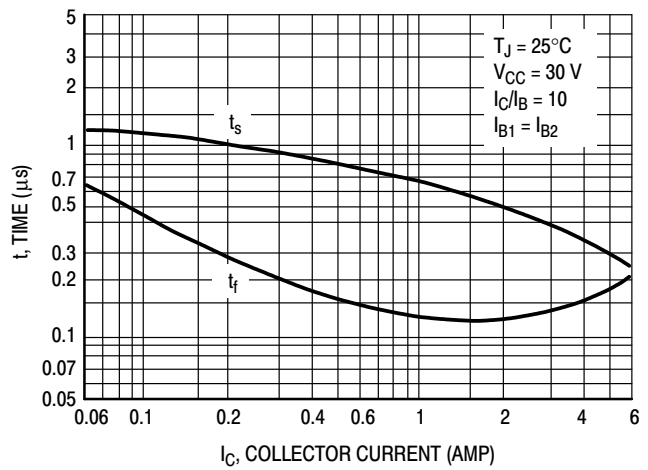


Figure 5. Turn-Off Time

MJD2955 (PNP), MJD3055 (NPN)

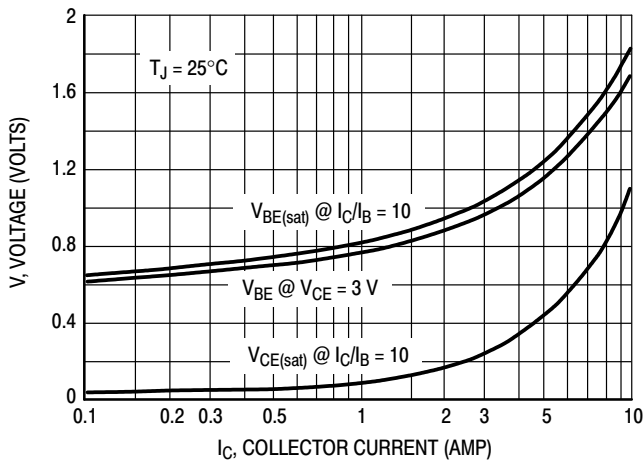


Figure 6. "On" Voltages, MJD2955

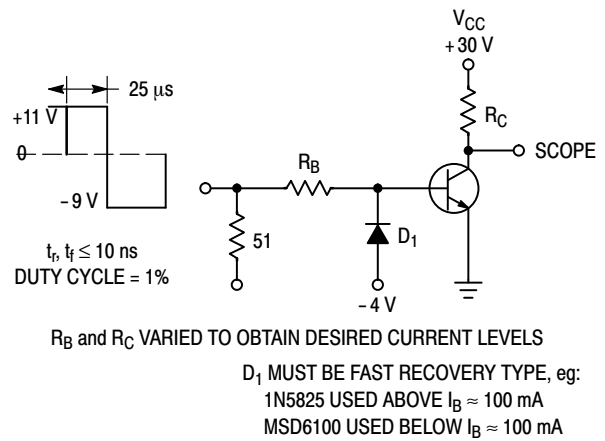


Figure 7. Switching Time Test Circuit

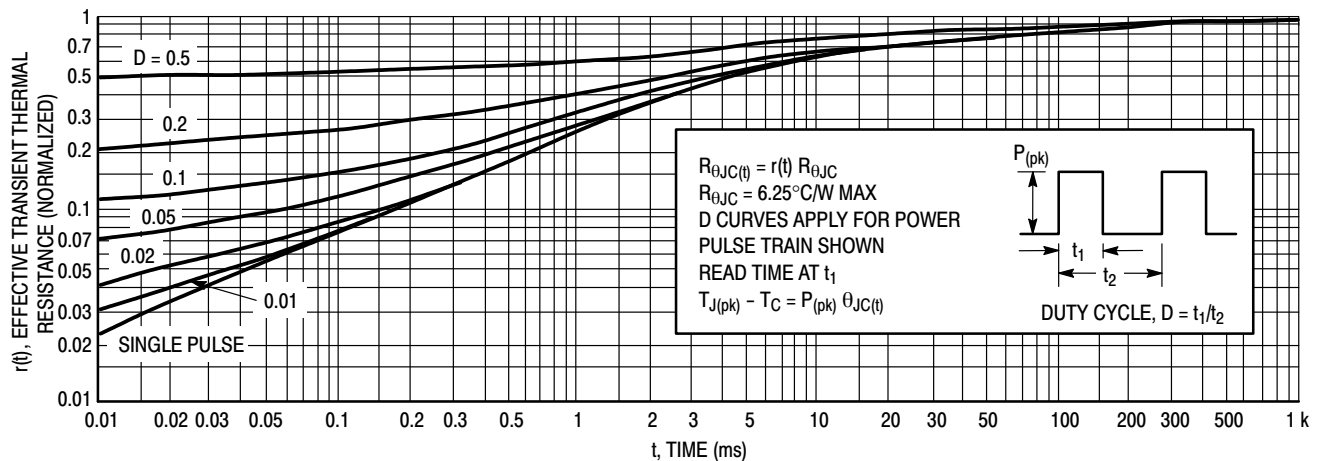


Figure 8. Thermal Response

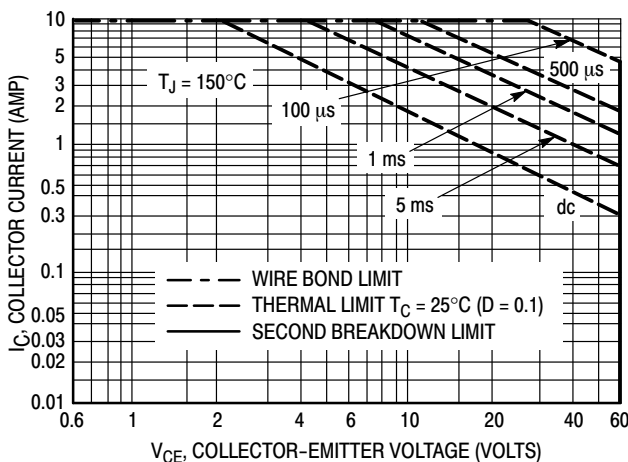


Figure 9. Maximum Forward Bias Safe Operating Area

Forward Bias Safe Operating Area Information

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 9 is based on $T_{J(pk)} = 150^\circ\text{C}$; T_C is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} \leq 150^\circ\text{C}$. $T_{J(pk)}$ may be calculated from the data in Figure 8. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

MJD2955 (PNP), MJD3055 (NPN)

ORDERING INFORMATION

| Device | Package Type | Package | Shipping [†] |
|----------------|-------------------|---------|-----------------------|
| MJD2955G | DPAK (Pb-Free) | 369C | 75 Units / Rail |
| MJD2955-1G | IPAK (Pb-Free) | 369D | 75 Units / Rail |
| MJD2955T4G | DPAK (Pb-Free) | 369C | 2,500 / Tape & Reel |
| NJVMJD2955T4G* | DPAK (Pb-Free) | 369C | 2,500 / Tape & Reel |
| MJD3055G | DPAK (Pb-Free) | 369C | 75 Units / Rail |
| MJD3055T4G | DPAK (Pb-Free) | 369C | 2,500 / Tape & Reel |
| NJVMJD3055T4G* | DPAK (Pb-Free) | 369C | 2,500 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable

MECHANICAL CASE OUTLINE

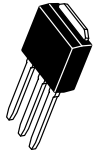
PACKAGE DIMENSIONS

ON Semiconductor®



IPAK CASE 369D-01 ISSUE C

DATE 15 DEC 2010



SCALE 1:1



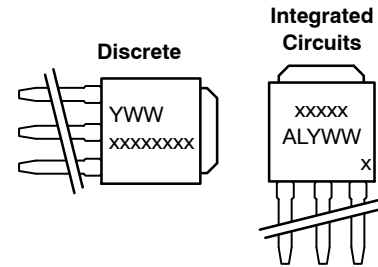
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

| DIM | INCHES | | MILLIMETERS | |
|-----|--------|-------|-------------|------|
| | MIN | MAX | MIN | MAX |
| A | 0.235 | 0.245 | 5.97 | 6.35 |
| B | 0.250 | 0.265 | 6.35 | 6.73 |
| C | 0.086 | 0.094 | 2.19 | 2.38 |
| D | 0.027 | 0.035 | 0.69 | 0.88 |
| E | 0.018 | 0.023 | 0.46 | 0.58 |
| F | 0.037 | 0.045 | 0.94 | 1.14 |
| G | 0.090 | BSC | 2.29 | BSC |
| H | 0.034 | 0.040 | 0.87 | 1.01 |
| J | 0.018 | 0.023 | 0.46 | 0.58 |
| K | 0.350 | 0.380 | 8.89 | 9.65 |
| R | 0.180 | 0.215 | 4.45 | 5.45 |
| S | 0.025 | 0.040 | 0.63 | 1.01 |
| V | 0.035 | 0.050 | 0.89 | 1.27 |
| Z | 0.155 | --- | 3.93 | --- |

MARKING DIAGRAMS

- STYLE 1:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR
- STYLE 2:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN
- STYLE 3:
PIN 1. ANODE
2. CATHODE
3. ANODE
4. CATHODE
- STYLE 4:
PIN 1. CATHODE
2. ANODE
3. GATE
4. ANODE
- STYLE 5:
PIN 1. GATE
2. ANODE
3. CATHODE
4. ANODE
- STYLE 6:
PIN 1. MT1
2. MT2
3. GATE
4. MT2
- STYLE 7:
PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

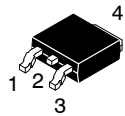


- xxxxxxxx = Device Code
- A = Assembly Location
- IL = Wafer Lot
- Y = Year
- WW = Work Week

| | | |
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| DESCRIPTION: | IPAK (DPAK INSERTION MOUNT) | PAGE 1 OF 1 |

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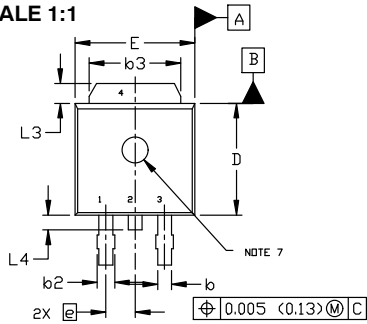
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



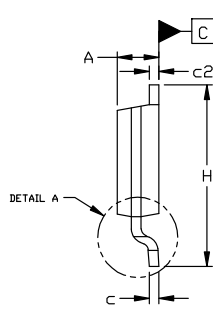
DPAK (SINGLE GAUGE) CASE 369C ISSUE G

DATE 31 MAY 2023

SCALE 1:1



TOP VIEW

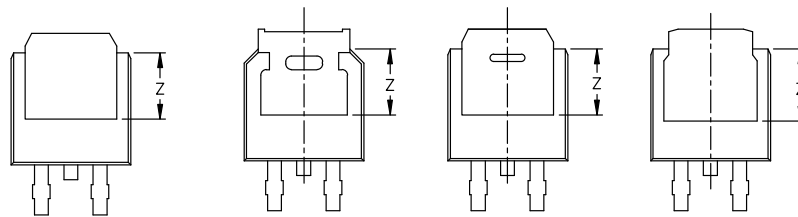


SIDE VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3, AND Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
7. OPTIONAL MOLD FEATURE.

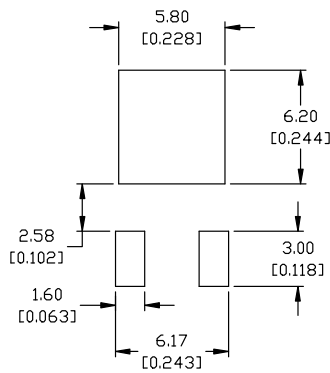
| DIM | INCHES | | MILLIMETERS | |
|-----|--------|-------|-------------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| A | 0.086 | 0.094 | 2.18 | 2.38 |
| A1 | 0.000 | 0.005 | 0.00 | 0.13 |
| b | 0.025 | 0.035 | 0.63 | 0.89 |
| b2 | 0.028 | 0.045 | 0.72 | 1.14 |
| b3 | 0.180 | 0.215 | 4.57 | 5.46 |
| c | 0.018 | 0.024 | 0.46 | 0.61 |
| c2 | 0.018 | 0.024 | 0.46 | 0.61 |
| D | 0.235 | 0.245 | 5.97 | 6.22 |
| E | 0.250 | 0.265 | 6.35 | 6.73 |
| e | 0.090 | BSC | 2.29 | BSC |
| H | 0.370 | 0.410 | 9.40 | 10.41 |
| L | 0.055 | 0.070 | 1.40 | 1.78 |
| L1 | 0.114 | REF | 2.90 | REF |
| L2 | 0.020 | BSC | 0.51 | BSC |
| L3 | 0.035 | 0.050 | 0.89 | 1.27 |
| L4 | --- | 0.040 | --- | 1.01 |
| Z | 0.155 | --- | 3.93 | --- |



BOTTOM VIEW

BOTTOM VIEW

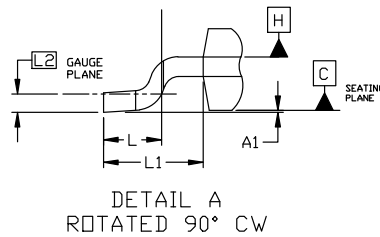
ALTERNATE CONSTRUCTIONS



RECOMMENDED MOUNTING FOOTPRINT*

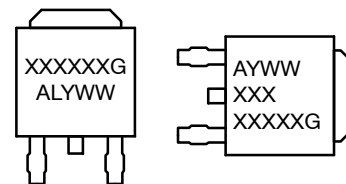
*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

- | | | | | |
|--|--|---|---|--|
| <p>STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR</p> | <p>STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN</p> | <p>STYLE 3: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE</p> | <p>STYLE 4: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE</p> | <p>STYLE 5: PIN 1. GATE 2. ANODE 3. CATHODE 4. ANODE</p> |
| <p>STYLE 6: PIN 1. MT1 2. MT2 3. GATE 4. MT2</p> | <p>STYLE 7: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR</p> | <p>STYLE 8: PIN 1. N/C 2. CATHODE 3. ANODE 4. CATHODE</p> | <p>STYLE 9: PIN 1. ANODE 2. CATHODE 3. RESISTOR ADJUST 4. CATHODE</p> | <p>STYLE 10: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. ANODE</p> |



DETAIL A
ROTATED 90° CW

GENERIC MARKING DIAGRAM*



- | | |
|---------|----------|
| IC | Discrete |
| XXXXXXG | AYWWXXX |
| XXXXXX | XXX |
| A | XXXXXXG |
| L | |
| Y | |
| WW | |
| G | |
- XXXXXX = Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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| DESCRIPTION: | DPAK (SINGLE GAUGE) | PAGE 1 OF 1 |

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